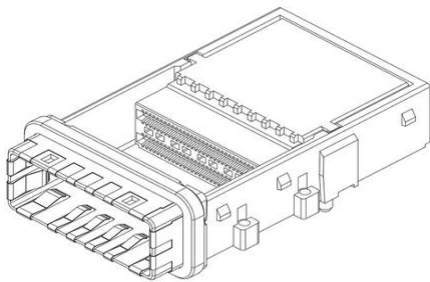




Part Number : [1733590001](#)
Product Description : zCD (CDFP) Short Body
Connector Assembly, 16X, 120 Circuits, 0.75mm Pitch,
with EMI Fingers and EMI Gasket, Gold (Au) Over Nickel
Plated
Series Number : 173359
Status : Active
Product Category : High-Speed I/O Connectors



Documents & Resources

Drawings

[1733590001 sd.pdf](#)

3D Models and Design Files

[STEP AP242](#)

[SOLIDWORKS](#)

[Creo](#)

Specifications

[AS-173359-0001-001.pdf](#)

[AS-173359-0002-001.pdf](#)

[PK-170834-0001-001.pdf](#)

[PS-173359-0001-001.pdf](#)


Tooling Specifications

[ATS-622030700-001.pdf](#)

[ATS-622030750-001.pdf](#)

Product Environment Compliance

Compliance

GADSL/IMDS	Not Relevant
China RoHS	 per SJ/T 11365-2006
EU ELV	Not Relevant
Low-Halogen Status	Low-Halogen per IEC 61249-2-21

REACH SVHC	Not Contained per D(2025)4165-DC (25 June 2025)
EU RoHS	Compliant per EU 2015/863

Compliance Statements

- EU RoHS
- REACH SVHC
- Low-Halogen

Industry Documents

- IPC 1752A Class C
- IPC 1752A Class D
- Molex Product Compliance Declaration
- IEC-62474
- chemSHERPA (xml)

Substances of Interest

- PFAS

EU RoHS Certificate of Compliance

Additional Product Compliance Information

Part Details

General

Status	Active
Category	High-Speed I/O Connectors
Series	173359
Description	zCD (CDFP) Short Body Connector Assembly, 16X, 120 Circuits, 0.75mm Pitch, with EMI Fingers and EMI Gasket, Gold (Au) Over Nickel Plated
Application	Wire-to-Board
Component Type	Receptacle
Product Name	CDFP,zCD
Type	Pluggable
UPC	889056590587

Agency

UL	E29179
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Electrical

Current - Maximum per Contact	1.0A
Data Rate	28.0 Gbps
Grounding to Panel	Bezel
Shielded	Yes
Shield Type	EMI Fingers, EMI Gasket
Voltage - Maximum	30V AC (RMS)/DC

Physical

Circuits (Loaded)	120
Color - Resin	Black
Durability (mating cycles max)	50
Flammability	94V-0
Gender	Female
Keying to Mating Part	None
Lock to Mating Part	Yes
Material - Metal	Copper Alloy
Material - Plating Mating	Gold
Material - Plating Termination	Tin
Material - Resin	High Temperature Thermoplastic
Net Weight	34.205/g
Number of Rows	4
Orientation	Right Angle
Packaging Type	Tray
Panel Mount	Yes
PCB Locator	Yes
PCB Retention	Yes
PCB Thickness - Recommended	1.57mm
Pitch - Mating Interface	0.75mm
Plating min - Mating	0.762µm
Plating min - Termination	0.762µm
Polarized to Mating Part	Yes
Polarized to PCB	Yes
Ports	1
Temperature Range - Operating	-40° to +85°C

Termination Interface Style	Through Hole - Compliant Pin
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Solder Process Data

Lead-Free Process Capability	N/A
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Mates With / Use With

Mates with Part(s)

Description	Part Number
zCD-to-zCD (CDFP-to-CDFP) Cable Assemblies	<u>201069</u>

Application Tooling